

## Claims

What is claimed is:

- 1 1. An electronic structure, comprising:  
2 a substrate, wherein the substrate is divided into a plurality of segments, and  
3 a semiconductor device electrically coupled to each of the segments.
- 1 2. The electronic structure of claim 1, wherein the semiconductor device is symmetrically coupled  
2 to each segment.
- 1 3. The electronic structure of claim 1, wherein the semiconductor device is not symmetrically  
2 coupled to each segment.
- 1 4. The electronic structure of claim 1, wherein a first segment and a second segment of the  
2 plurality of segments are congruent with respect to each other.
- 1 5. The electronic structure of claim 1, wherein a first segment and a second segment of the  
2 plurality of segments are not congruent with respect to each other.
- 1 6. The electronic structure of claim 1, wherein the plurality of segments are square segments.

1 7. The electronic structure of claim 1, wherein the plurality of segments consists of 4 segments.

1 8. The electronic structure of claim 1, wherein the substrate is a chip carrier, and wherein the  
2 semiconductor device is a semiconductor chip.

1     9. An electronic structure, comprising:  
2         a substrate; and  
3         a semiconductor device electrically coupled to the substrate, wherein the semiconductor is  
4     divided into a plurality of segments.

1     10. The electronic structure of claim 9, wherein the length of each segment of the semiconductor  
2     device is greater than or equal to 5 millimeters.

1     11. The electronic structure of claim 9, wherein a first segment and a second segment of the  
2     plurality of segments are congruent with respect to each other.

1     12. The electronic structure of claim 9, wherein a first segment and a second segment of the  
2     plurality of segments are not congruent with respect to each other.

1     13. The electronic structure of claim 9, wherein the plurality of segments are square segments.

1 14. A method for forming an electronic structure, comprising:  
2 dividing a substrate into a plurality of segments, and  
3 electrically coupling a semiconductor device to each segment of the plurality of segments  
4 of the substrate.

1 15. The method of claim 14, wherein the semiconductor device is symmetrically coupled to each  
2 segment.

1 16. The method of claim 14, wherein the semiconductor device is not symmetrically coupled to  
2 each segment.

1 17. The method of claim 14, wherein a first segment and a second segment of the plurality of  
2 segments are congruent with respect to each other.

1 18. The method of claim 14, wherein a first segment and a second segment of the plurality of  
2 segments are not congruent with respect to each other.

1 19. The method of claim 14, wherein the plurality of segments consists of 4 segments.

1 20. The method of claim 15, wherein the plurality of segments are square segments.